

Power Schottky rectifier

Features

- very small conduction losses
- negligible switching losses
- extremely fast switching
- avalanche capability specified

Description

Dual center tap Schottky rectifier suited for switch mode power supply and high frequency DC to DC converters.

Packaged either in TO-220AB, D²PAK, I²PAK, or DPAK, this device is especially intended for use in low voltage, high frequency inverters, free wheeling and polarity protection applications.

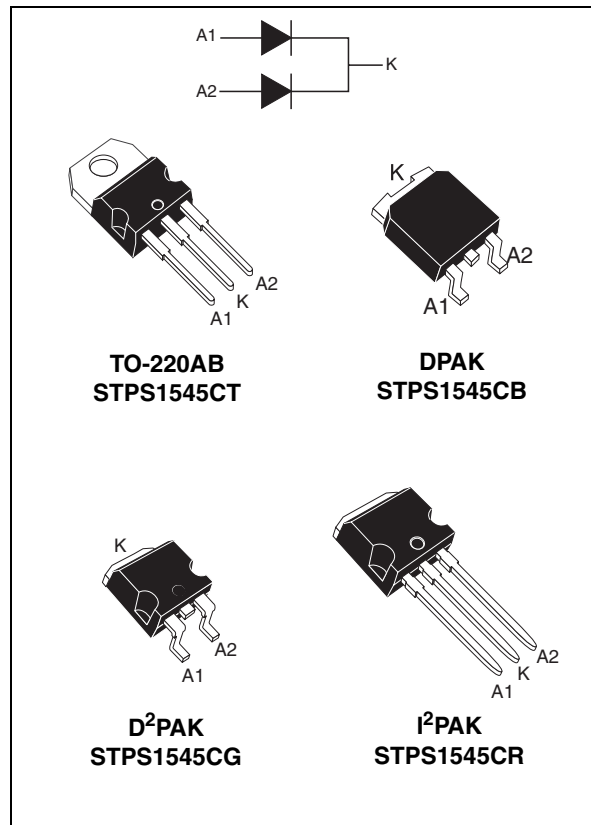


Table 1. Device summary

| | |
|-------------|-----------|
| $I_{F(AV)}$ | 2 x 7.5 A |
| V_{RRM} | 45 V |
| T_j (max) | 175 °C |
| V_F (max) | 0.57 V |

1 Characteristics

Table 2. Absolute ratings (limiting values)

| Symbol | Parameter | | | Value | Unit | |
|----------------------|---|--|-----------|---|------------|---|
| V _R RM | Repetitive peak reverse voltage | | | 45 | V | |
| I _F (RMS) | Forward rms current | | | 20 | A | |
| I _F (AV) | Average forward current $\delta = 0.5$ | T _c = 157 °C | Per diode | 7.5 | A | |
| I _F SM | Surge non repetitive forward current | | | t _p = 10 ms sinusoidal | 150 | A |
| I _R RM | Peak repetitive reverse current | t _p = 2 μ s square F = 1 kHz | | 1 | A | |
| I _R SM | Non repetitive peak reverse current | | | t _p = 100 μ s square | 2 | A |
| P _{ARM} | Repetitive peak avalanche power | | | t _p = 1 μ s T _j = 25 °C | 2700 | W |
| T _{stg} | Storage temperature range | | | -65 to + 175 | °C | |
| T _j | Maximum operating junction temperature ⁽¹⁾ | | | 175 | °C | |
| dV/dt | Critical rate of rise of reverse voltage | | | 10000 | V/ μ s | |

1. $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal resistances

| Symbol | Parameter | | Value | Unit |
|----------------------|------------------|--------------------|------------|------|
| R _{th(j-c)} | Junction to case | Per diode Total | 3.0 1.7 | °C/W |
| R _{th(c)} | Coupling | | 0.35 | |

When the diodes 1 and 2 are used simultaneously:

$$\Delta T_j(\text{diode 1}) = P(\text{diode1}) \times R_{th(j-c)}(\text{Per diode}) + P(\text{diode2}) \times R_{th(c)}$$

Table 4. Static electrical characteristics (per diode)

| Symbol | Parameter | Test conditions | | Min. | Typ. | Max. | Unit |
|-------------------------------|-------------------------|-------------------------|------------------------------------|------|------|------|---------|
| I _R ⁽¹⁾ | Reverse leakage current | T _j = 25 °C | V _R = V _R RM | - | - | 100 | μ A |
| | | T _j = 125 °C | | - | 5 | 15 | mA |
| V _F ⁽¹⁾ | Forward voltage drop | T _j = 125°C | I _F = 7.5A | - | 0.5 | 0.57 | V |
| | | T _j = 25°C | I _F = 15 A | - | - | 0.84 | |
| | | T _j = 125 °C | I _F = 15 A | - | 0.65 | 0.72 | |

1. Pulse test: t_p = 380 μ s, $\delta < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 0.42 \times I_{F(AV)} + 0.020 I_{F(RMS)}^2$$

Figure 1. Average forward power dissipation versus average forward current (per diode)

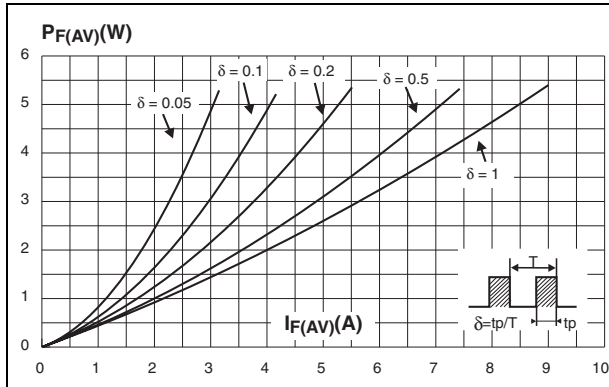


Figure 2. Average forward current versus ambient temperature (delta = 0.5, per diode)

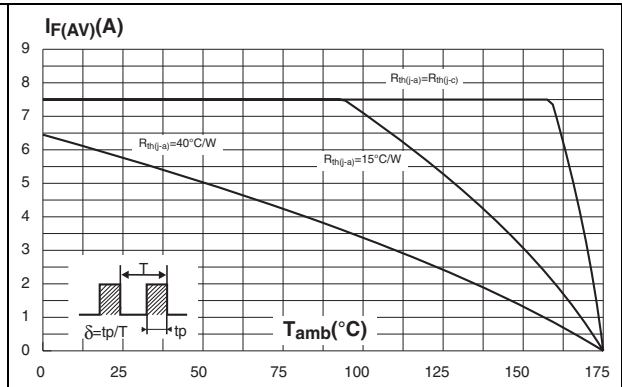


Figure 3. Normalized avalanche power derating versus pulse duration

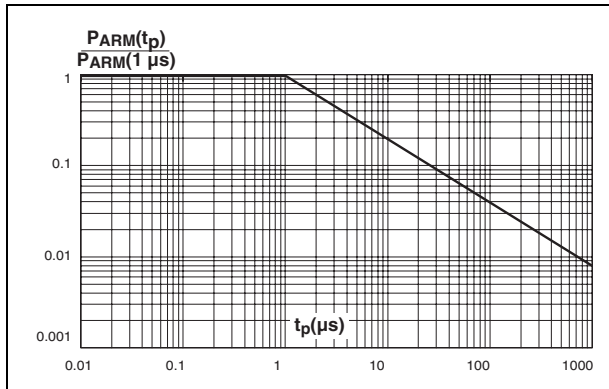


Figure 4. Normalized avalanche power derating versus junction temperature

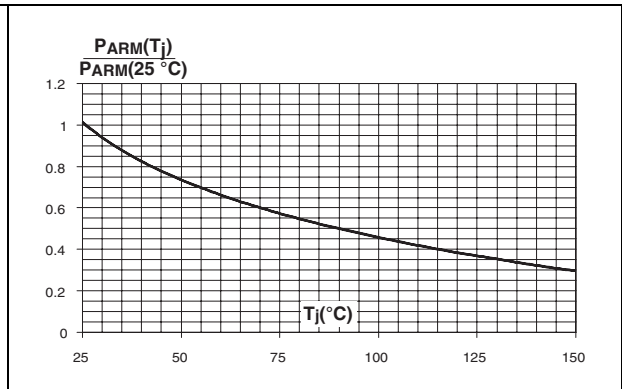


Figure 5. Non repetitive surge peak forward current versus overload duration (maximum values, per diode)

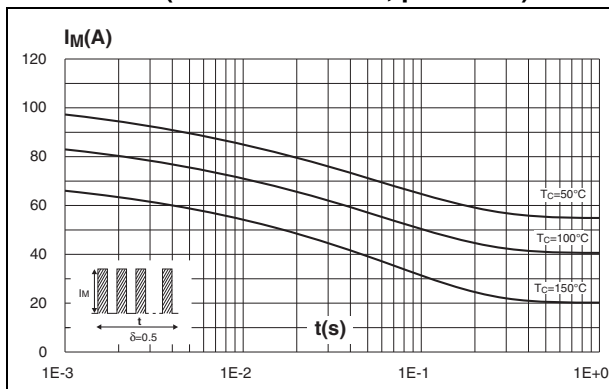


Figure 6. Relative variation of thermal impedance junction to case versus pulse duration

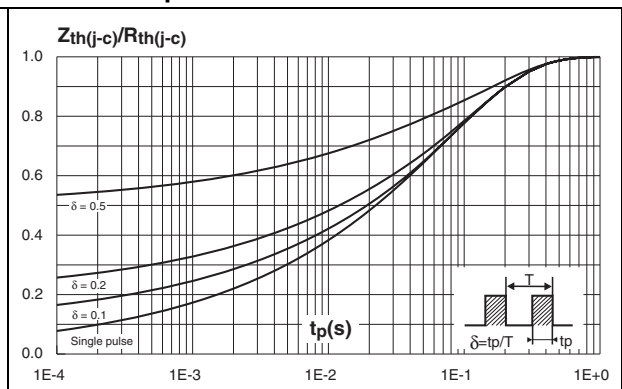


Figure 7. Reverse leakage current versus reverse voltage applied (typical values, per diode)

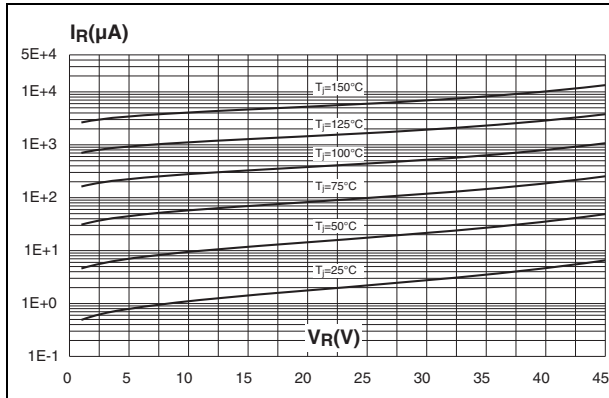


Figure 8. Junction capacitance versus reverse voltage applied (typical values, per diode)

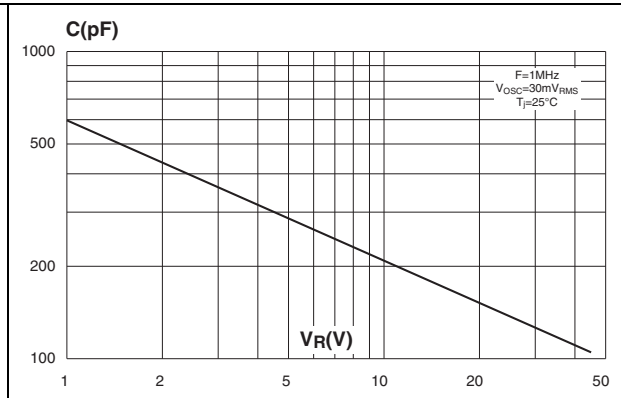


Figure 9. Forward voltage drop versus forward current (high values, per diode)

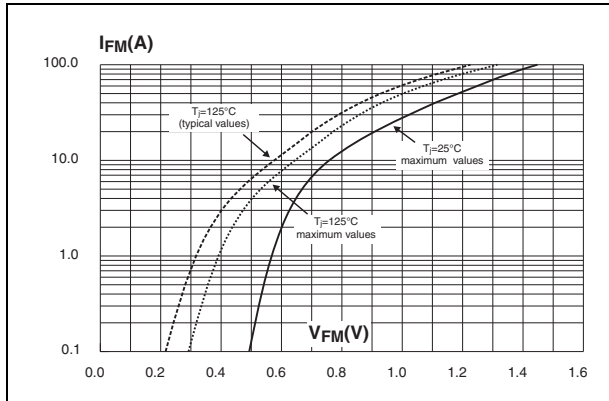


Figure 10. Thermal resistance junction to ambient versus copper surface under tab (D²PAK)

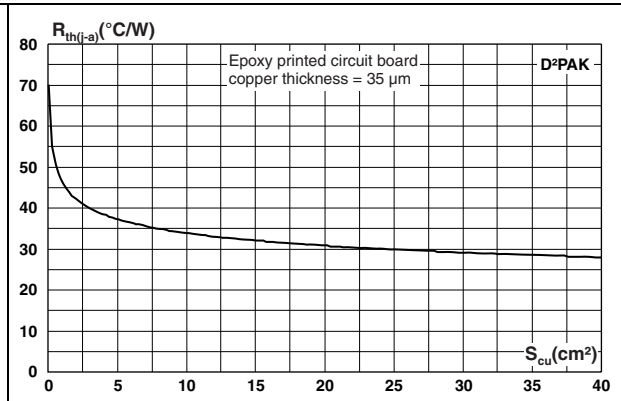
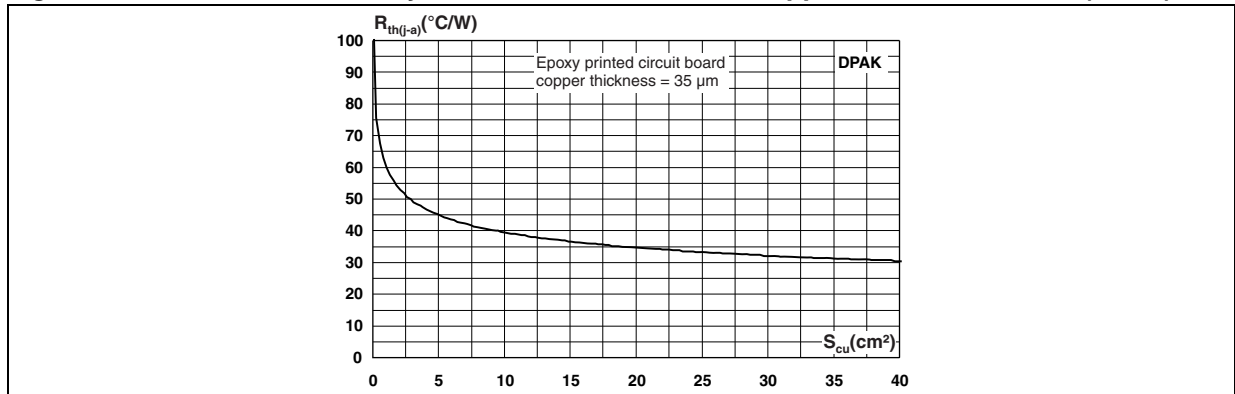


Figure 11. Thermal resistance junction to ambient versus copper surface under tab (DPAK)



2 Package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.4 to 0.6 N·m

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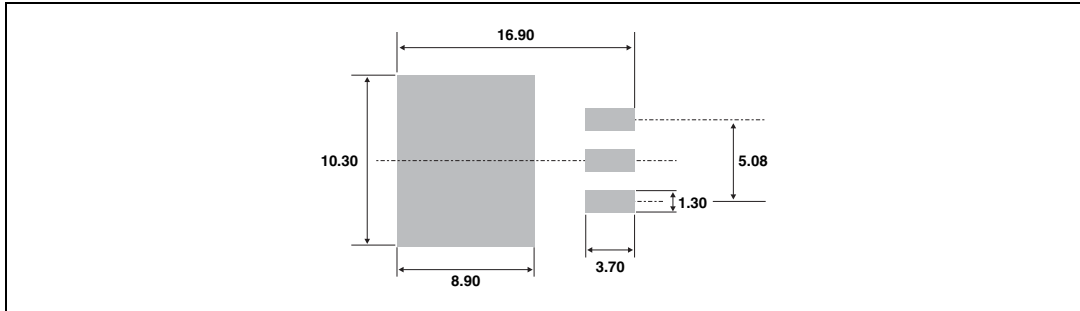
Figure 12. TO-220AB dimensions

| Ref | Dimensions | | | |
|------|-------------|-------|------------|-------|
| | Millimeters | | Inches | |
| | Min. | Max. | Min. | Max. |
| A | 4.40 | 4.60 | 0.173 | 0.181 |
| C | 1.23 | 1.32 | 0.048 | 0.051 |
| D | 2.40 | 2.72 | 0.094 | 0.107 |
| E | 0.49 | 0.70 | 0.019 | 0.027 |
| F | 0.61 | 0.88 | 0.024 | 0.034 |
| F1 | 1.14 | 1.70 | 0.044 | 0.066 |
| F2 | 1.14 | 1.70 | 0.044 | 0.066 |
| G | 4.95 | 5.15 | 0.194 | 0.202 |
| G1 | 2.40 | 2.70 | 0.094 | 0.106 |
| H2 | 10 | 10.40 | 0.393 | 0.409 |
| L2 | 16.4 typ. | | 0.645 typ. | |
| L4 | 13 | 14 | 0.511 | 0.551 |
| L5 | 2.65 | 2.95 | 0.104 | 0.116 |
| L6 | 15.25 | 15.75 | 0.600 | 0.620 |
| L7 | 6.20 | 6.60 | 0.244 | 0.259 |
| L9 | 3.50 | 3.93 | 0.137 | 0.154 |
| M | 2.6 typ. | | 0.102 typ. | |
| Dia. | 3.75 | 3.85 | 0.147 | 0.151 |

Table 5. D²PAK dimensions

| Ref. | Dimensions | | | |
|------|-------------|-------|------------|-------|
| | Millimeters | | Inches | |
| | Min. | Max. | Min. | Max. |
| A | 4.40 | 4.60 | 0.173 | 0.181 |
| A1 | 2.49 | 2.69 | 0.098 | 0.106 |
| A2 | 0.03 | 0.23 | 0.001 | 0.009 |
| B | 0.70 | 0.93 | 0.027 | 0.037 |
| B2 | 1.14 | 1.70 | 0.045 | 0.067 |
| C | 0.45 | 0.60 | 0.017 | 0.024 |
| C2 | 1.23 | 1.36 | 0.048 | 0.054 |
| D | 8.95 | 9.35 | 0.352 | 0.368 |
| E | 10.00 | 10.40 | 0.393 | 0.409 |
| G | 4.88 | 5.28 | 0.192 | 0.208 |
| L | 15.00 | 15.85 | 0.590 | 0.624 |
| L2 | 1.27 | 1.40 | 0.050 | 0.055 |
| L3 | 1.40 | 1.75 | 0.055 | 0.069 |
| M | 2.40 | 3.20 | 0.094 | 0.126 |
| R | 0.40 typ. | | 0.016 typ. | |
| V2 | 0° | 8° | 0° | 8° |

Figure 13. Footprint (dimensions in millimeters)



Mounting (soldering) the I²PAK metal slug (heatsink) with alloy, like a surface mount device, IS NOT PERMITTED. A standard through-hole mounting is mandatory.

Figure 14. I²PAK dimensions

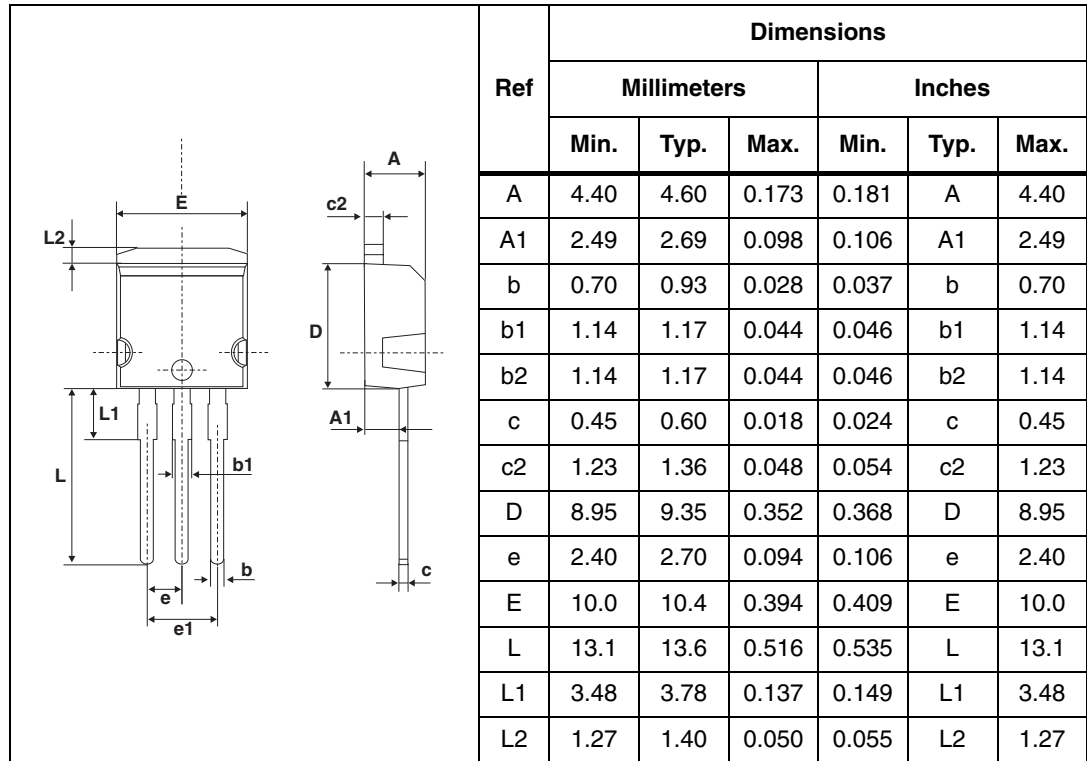
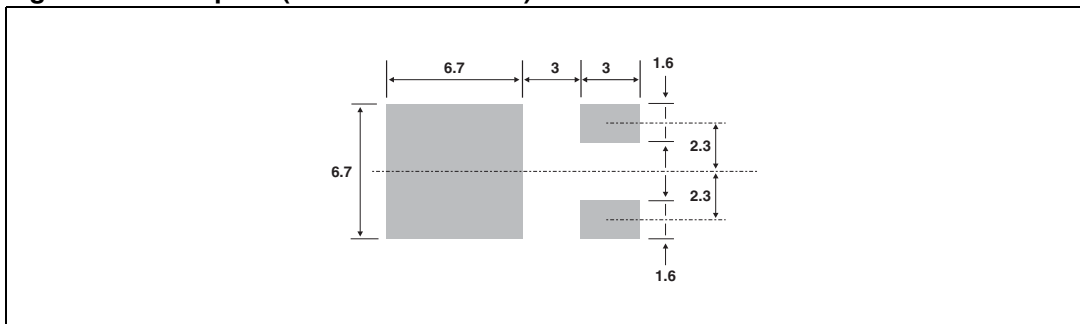


Table 6. DPAK dimensions

| Ref. | Dimensions | | | |
|------|-------------|-------|------------|-------|
| | Millimeters | | Inches | |
| | Min. | Max. | Min. | Max. |
| A | 2.20 | 2.40 | 0.086 | 0.094 |
| A1 | 0.90 | 1.10 | 0.035 | 0.043 |
| A2 | 0.03 | 0.23 | 0.001 | 0.009 |
| B | 0.64 | 0.90 | 0.025 | 0.035 |
| B2 | 5.20 | 5.40 | 0.204 | 0.212 |
| C | 0.45 | 0.60 | 0.017 | 0.023 |
| C2 | 0.48 | 0.60 | 0.018 | 0.023 |
| D | 6.00 | 6.20 | 0.236 | 0.244 |
| E | 6.40 | 6.60 | 0.251 | 0.259 |
| G | 4.40 | 4.60 | 0.173 | 0.181 |
| H | 9.35 | 10.10 | 0.368 | 0.397 |
| L2 | 0.80 typ. | | 0.031 typ. | |
| L4 | 0.60 | 1.00 | 0.023 | 0.039 |
| V2 | 0° | 8° | 0° | 8° |

Figure 15. Footprint (dimensions in mm)



3 Ordering information

Table 7. Ordering information

| Order code | Marking | Package | Weight | Base qty | Delivery mode |
|---------------|------------|--------------------|--------|----------|---------------|
| STPS1545CT | STPS1545CT | TO-220AB | 2.23 g | 50 | Tube |
| STPS1545CG | STPS1545CG | D ² PAK | 1.48 g | 50 | Tube |
| STPS1545CG-TR | STPS1545CG | D ² PAK | 1.48 g | 1000 | Tape and reel |
| STPS1545CR | STPS1545CR | I ² PAK | 1.49 g | 50 | Tube |
| STPS1545CB-TR | STPS1545CB | DPAK | 0.3 g | 2500 | Tape and reel |

For the latest information on available order codes see the product pages on www.st.com.

4 Revision history

Table 8. Document revision history

| Date | Revision | Changes |
|-------------|----------|--|
| Jul-2003 | 5F | Last release. |
| 21-Mar-2007 | 6 | Removed ISOWATT and TO-220FPAB packages. |
| 03-Nov-2010 | 7 | Added DPAK package. |

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